

Amendments to the Specification:

Please amend the paragraph on page 1, beginning on line 17, as follows:

--According to the mounting technique disclosed in the above-mentioned patent publication, as shown in Fig. 1, in order to electrically amplify display signals fed from a printed board (circuit board) 12 and to supply the signals to a plurality of column electrodes provided on a rear glass substrate 5 of a display section main body [[2]], wiring connection is formed between the display section main body [[2]] and the circuit board 12 provided on the backside of a metal chassis [[3]], by virtue of a TCP 8 containing an integrated circuit device 9 (driver IC) for power amplification.--

Please amend the paragraph on page 2, beginning on line 5, as follows:

--Then, the column electrode terminals formed on the side edge 7 of the rear glass substrate 5 are connected to the end portions of the wiring patterns formed on an end portion 8a of the TCP 8, the TCP8 is drawn to the rear side of the metal chassis [[3]] to fix the driver IC 9 to the metal chassis [[3]], and another end portion of the TCP8 is connected to the circuit board 12, thereby realizing the wiring connection between the circuit board 12 and the display section main body [[2]] through the TCP 8.--

Please amend the paragraph on page 13, beginning on line 9, as follows:

--When the display section main body [[20]] is wire-connected to the circuit board 40, as shown in Fig. 5, the connecting terminals CA1–CAk, CB11–CB1m, and CB21–CB2n of the first and second terminal groups GR1, GR2 are made coincident (in position) with the connecting terminals CE1–CEk, CF11–CF1m and CF21–CF2n formed

in the connection end portion 52 of the TCP50. Meanwhile, using an anisotropic conductive adhesive agent and by virtue of thermo-press bonding, the first and second terminal groups GR1, GR2 are connected mechanically and electrically to the connecting terminals CE1–CEk, CF11–CF1m, and CF21–CF2n of the TCP 50 in only one step of operation. Subsequently, the TCP 50 is fixed to the rear glass substrate 22 side by means of damp-proof adhesive agents P1 and P2, as shown in Fig. 2.--